

VERSION OF SPECIFICATION WITH MARKINGS TO SHOW CHANGES MADE

[0001] This application is a continuation of application Serial No. 09/651,460, filed August 30, 2000, [pending]now U.S. Patent 6,295,209 B1, issued September 25, 2001, which is a continuation of application Serial No. 09/464,992, filed December 16, 1999, now U.S. Patent 6,144,560, issued November 7, 2000, which is a continuation of application Serial No. 09/296,952, filed April 22, 1999, now U.S. Patent 6,091,606, issued July 18, 2000, which is a continuation of application Serial No. 09/002,063, filed December 31, 1997, now U.S. Patent 5,940,277, issued August 17, 1999.

VERSION OF CLAIMS WITH MARKINGS TO SHOW CHANGES MADE

4. (Amended) The semiconductor device of claim 1, wherein said[at least one] notch is tapered from a surface of said layer toward said surface of the semiconductor device.
6. (Amended) The semiconductor device of claim 1, wherein said[at least one] notch substantially surrounds said at least one contact pad.
13. (Amended) The protective layer of claim 12, further comprising a bevel along said edge.
19. (Amended) The protective layer of claim 12, wherein said substantially planar [structure]member is configured to cover only a portion of a surface of the semiconductor device adjacent an edge thereof proximate to which at least one contact pad is located upon assembly of the protective layer with the semiconductor device.
21. (Amended) The protective layer of claim 12, wherein said at least one notch is configured to substantially surround the corresponding contact pad upon assembly of the protective layer with the semiconductor device.